

TOSHIBA Infrared LED GaAlAs Infrared Emitter

TLN233

Infrared LED for Space-Optical-Transmission

Unit: mm

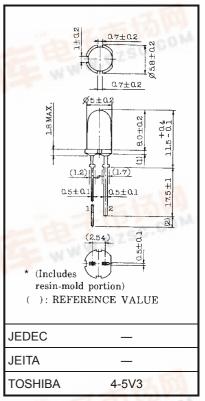
- High radiant intensity: 80 mW/sr (typ.) at I_F = 50 mA
- Half-angle value: $\theta 1/2 = \pm 13^{\circ}$ (typ.)
- A light source for remote control
- Wireless AV-signal transmission purpose
- DZSC.COM High speed data transmission purpose

Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Forward current	IF	100	mA	
Pulse forward current	I _{FP}	1000 (Note 1)	mA	
Power dissipation	PD	200	mW	
Reverse voltage	V _R	4	V	
Operating temperature range	T _{opr}	-25~85	°C	
Storage temperature range	T _{stg}	-30~100	°C	
Soldering temperature (5 s), (Note 2)	T _{sol}	260	°C	

Note 1: f = 100 kHz, duty = 1%

Note 2: Soldering must be performed under the stopper.



Pin Connection

1. Anode 2. Cathode



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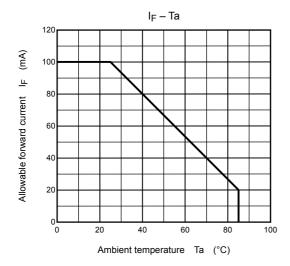
Optical and Electrical Characteristics (Ta = 25°C)

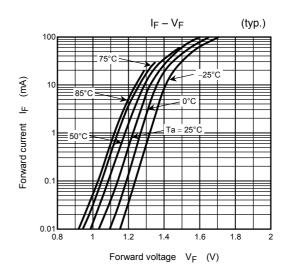
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _F	I _F = 100 mA	_	1.6	2.0	V
Reverse current	I _R	V _R = 4 V	_	_	60	μА
Radiant intensity	ΙE	I _F = 50 mA	46	80	_	mW/sr
Radiant power	PO	I _F = 50 mA	_	30	_	mW
Cut-off frequency	f _C	$I_F = 50 \text{ mA} + 5 \text{ mA}_{P-P}$ (Note 3)	_	15	_	MHz
Peak emission wavelength	λР	I _F = 50 mA	_	870	_	nm
Half-angle value	$\theta \frac{1}{2}$	I _F = 50 mA	_	±13		۰

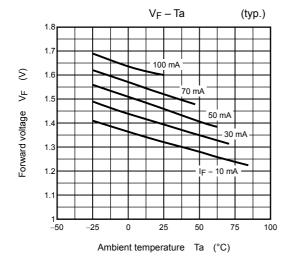
Note 3: Frequency when modulation light power decreases by 3dB from 1 MHz.

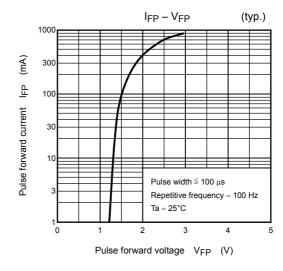
Handling Precautions

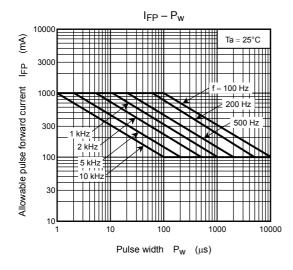
- Soldering must be performed under the stopper.
- When forming the leads, bend each lead under the 5 mm of package body. Soldering must be performed after the leads have been formed.
- The radiant intensity decrease over time due to current flowing in the infrared LED. When designing circuits, the device must take into account the change in radiant intensity over time. The change in radiant intensity is equal to the reciprocal of the change in LED infrared optical output. $\frac{IE\left(t\right)}{IE\left(0\right)} = \frac{P_{O}\left(t\right)}{P_{O}\left(0\right)}$

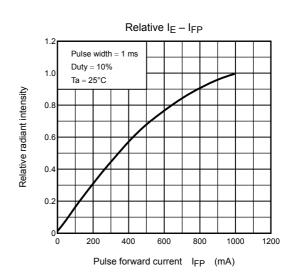




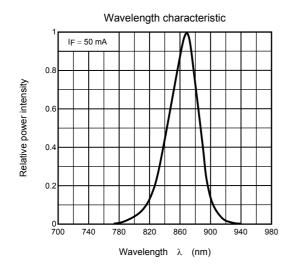


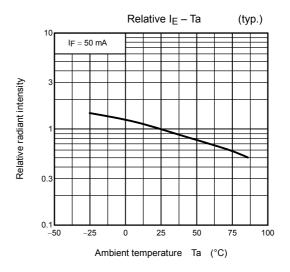


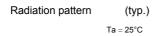


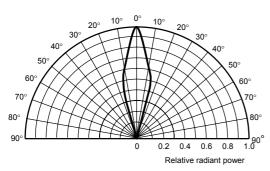


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